



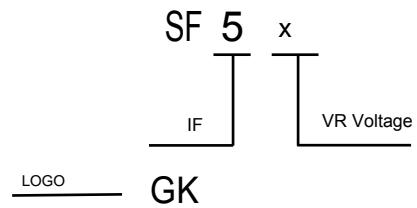
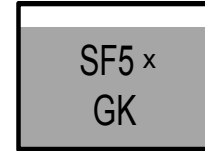
## FEATURES

- \* Low forward voltage drop
- \* High current capability
- \* High reliability
- \* High surge current capability

## MECHANICAL DATA

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Lead: Axial leads, solderable per MIL-STD-202, method 208 guranteed
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any

VOLTAGE RANGE  
50 to 600 Volts  
CURRENT  
5.0 Ampere



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unieess otherwies specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

TYPE NUMBER	SF51	SF52	SF53	SF54	SF55	SF56	SF58	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	150	200	300	400	600	V
Maximum RMS Voltage	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current	5.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	130							A
Maximum Instantaneous Forward Voltage at 5.0A	0.95				1.30	1.70		V
Maximum DC Reverse Current $T_a=25^{\circ}\text{C}$	5.0							$\mu\text{A}$
at Rated DC Blocking Voltage $T_a=100^{\circ}\text{C}$	50							$\mu\text{A}$
Maximum Reverse Recovery Time (Note 1)	35							nS
Typical Junction Capacitance (Note 2)	50							pF
Operating and Storage Temperature Range $T_J, T_{STG}$	-65 — +150							$^{\circ}\text{C}$

### NOTES:

1. Reverse Recovery Time test condition:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

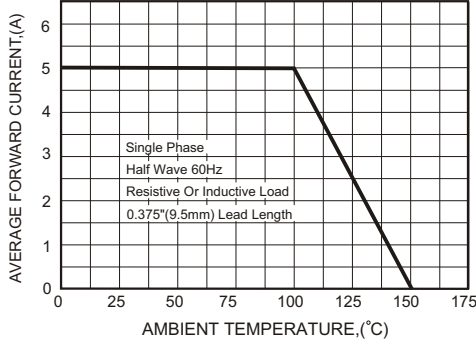


FIG.2-TYPICAL FORWARD CHARACTERISTICS

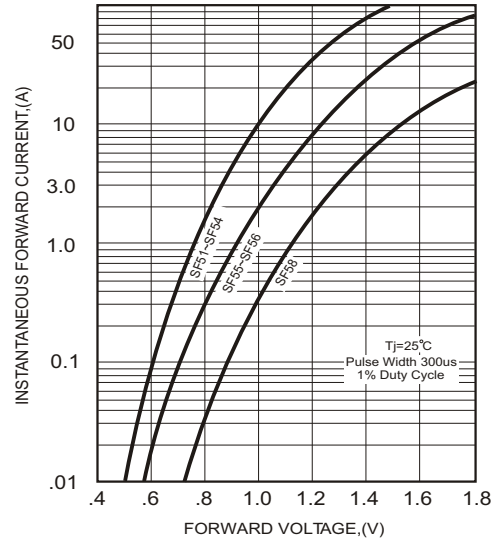
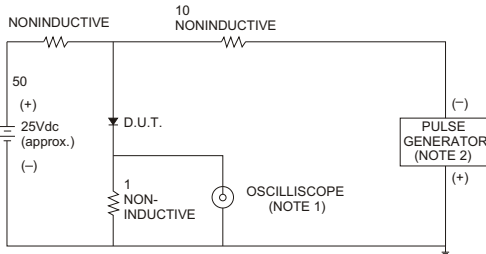


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

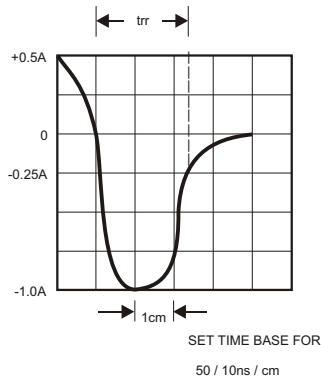


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

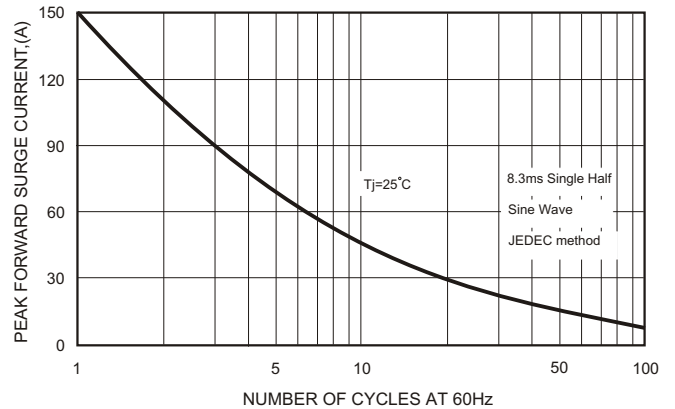


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

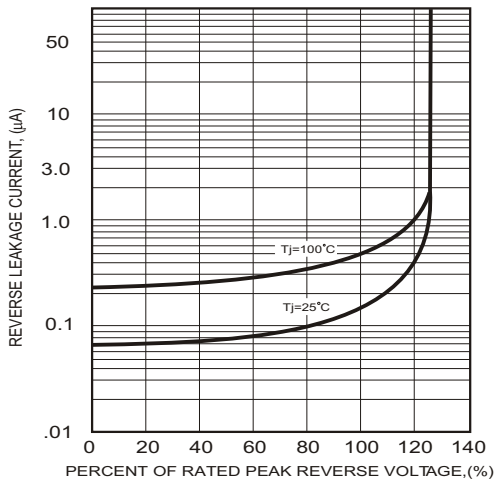
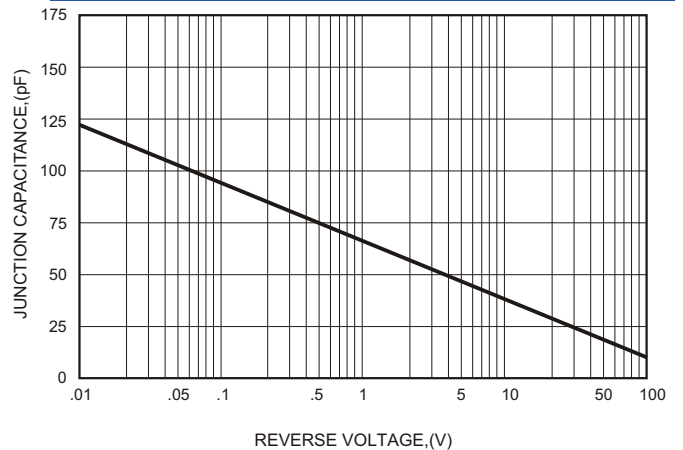


FIG.6-TYPICAL JUNCTION CAPACITANCE



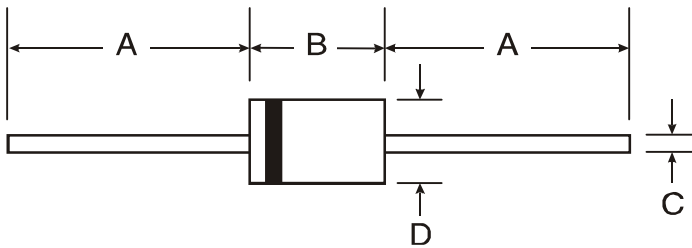
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150 °C
	-Temperature Max( $T_{s(max)}$ )	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3 °C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217 °C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

DO-27



DO-27		
Dim	Min	Max
A	24.00	-
B	7.20	9.50
C	1.15	1.25
D	5.00	5.60
All Dimensions in mm		